

NOV-12-2002 12:51

P.31/31
Wet
EV077333415
H72

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2827
Examiner David A. Zarneke
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

STATEMENT OF COMMON OWNERSHIP

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: D. Brent Kenady (Tel. 509-624-4276; Fax 509-838-3424)
Wells St. John P.S.
601 W. First Avenue, Suite 1300
Spokane, WA 99201-3828

Sir,

The above-referenced application and the reference (U.S. Patent No. 6,048,755 to Jiang et al.) presented as prior art in the Office Action mailed April 30, 2002 (Paper No. 9) were, at the time the invention was made, owned by or subject to an obligation of assignment to the same organization, Micron Technology, Inc. MPEP §706.02(l)(3).

The undersigned is an attorney of record.

Respectfully submitted,

Dated: 7-30-02

By: D. Brent Kenady
D. Brent Kenady
Reg. No. 40,045